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August 2018

FODM8061 High Noise Immunity, 3.3V/5V, 10Mbit/sec Logic Gate Output (Open Collector) Optocoupler

Features

- High Noise Immunity characterized by common mode transient immunity (CMTi)
 - 20kV/µs Minimum CMTi
- · High Speed
 - 10Mbit/sec Date Rate (NRZ)
 - 80ns max. Propagation Delay
 - 25ns max. Pulse Width Distortion
 - 40ns max. Propagation Delay Skew
- · 3.3V LVTTL/LVCMOS Compatibility
- Specifications guaranteed over 3V to 5.5V supply voltage and -40°C to +110°C temperature range
- · Safety and regulatory approvals
 - UL1577, 3750 VAC_{RMS} for 1 min.
 - DIN EN/IEC60747-5-5

Applications

- · Microprocessor system interface
 - SPI, I²C
- · Industrial fieldbus communications
 - DeviceNet, CAN, RS485
- · Programmable logic control
- · Isolated data acquisition system
- · Voltage level translator
- · Isolating MOSFET/IGBT gate drivers

Description

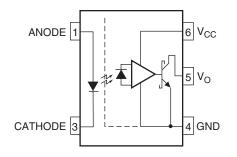
The FODM8061 is a 3.3V/5V high-speed logic gate output (open collector) optocoupler, which supports isolated communications allowing digital signals to communicate between systems without conducting ground loops or hazardous voltages. It utilizes Fairchild's patented coplanar packaging technology, Optoplanar[®], and optimized IC design to achieve high noise immunity, characterized by high common mode transient immunity specifications.

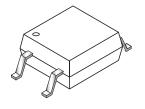
This optocoupler consists of an AlGaAS LED at the input, optically coupled to a high speed integrated photodetector logic gate. The output of the detector IC is an open collector schottky-clamped transistor. The coupled parameters are guaranteed over the wide temperature range of -40°C to +110°C. A maximum input signal of 5mA will provide a minimum output sink current of 13mA (fan out of 8).

Related Resources

- · www.fairchildsemi.com/products/opto/
- www.fairchildsemi.com/pf/FO/FODM611.html
- · www.fairchildsemi.com/pf/FO/FODM8071.html

Functional Schematic





Truth Table

LED	Output
Off	High
On	Low

Pin Definitions

Number	Name	Function Description
1	ANODE	Anode
3	CATHODE	Cathode
4	GND	Output Ground
5	Vo	Output Voltage
6	V _{CC}	Output Supply Voltage

Safety and Insulation Ratings for Mini-Flat Package (SO5 Pin)

As per IEC60747-5-2. This optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Symbol	Parameter	Min.	Тур.	Max.	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1				
	For rated main voltage < 150Vrms		I-IV		
	For rated main voltage < 300Vrms		1-111		
	Climatic Classification		40/110/21		
	Pollution Degree (DIN VDE 0110/1.89)		2		
CTI	Comparative Tracking Index	175			
V _{PR}	Input to Output Test Voltage, Method b, VIORM x 1.875 = V_{PR} , 100% Production Test with t_m = 1 sec, Partial Discharge < 5 pC	1060			
V_{PR}	Input to Output Test Voltage, Method a, VIORM x 1.5 = V_{PR} , Type and Sample Test with t_m = 60 sec, Partial Discharge < 5 pC	848			
V _{IORM}	Max Working Insulation Voltage	565			V _{peak}
V _{IOTM}	Highest Allowable Over Voltage	4000			V _{peak}
	External Creepage	5.0			mm
	External Clearance	5.0			mm
	Insulation thickness	0.5			mm
T _{Case}	Safety Limit Values, Maximum Values allowed in the event of a failure, Case Temperature	150			°C
R _{IO}	Insulation Resistance at T _S , V _{IO} = 500V	10 ⁹			Ω

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Units
T _{STG}	Storage Temperature	-40 to +125	°C
T _{OPR}	Operating Temperature	-40 to +110	°C
TJ	Junction Temperature	-40 to +125	°C
T _{SOL}	Lead Solder Temperature (Refer to Reflow Temperature Profile)	260 for 10sec	°C
I _F	Forward Current	50	mA
V _R	Reverse Voltage	5.0	V
V _{CC}	Supply Voltage	0 to 7.0	V
V _O	Output Voltage	-0.5 to V _{CC} +0.5	V
Io	Average Output Current	50	mA
PDI	Input Power Dissipation ⁽¹⁾⁽²⁾	100	mW
PD _O	Output Power Dissipation ⁽¹⁾⁽²⁾	85	mW

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
T _A	Ambient Operating Temperature	-40	+110	°C
V _{CC} , V _{DD}	Supply Voltages ⁽³⁾	3.0	5.5	V
V _{FL}	Logic Low Input Voltage	0	0.8	V
I _{FH}	Logic High Input Current ⁽⁴⁾	6.3	15	mA
I _{FL}	Logic Low Input Current		250	μA
N	Fan Out (at $R_L = 1k\Omega$)		5	TTL Loads
R_{L}	Output Pull-up Resistor	330	4k	Ω

Isolation Characteristics (T_A=25°C)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _{ISO}	Input-Output Isolation Voltage	freq= 60Hz, t = 1.0min, $I_{I-O} \le 10\mu A^{(5)(6)}$	3750			VAC _{RMS}
R _{ISO}	Isolation Resistance	$V_{I-O} = 500V^{(5)}$		10 ¹²		Ω
C _{ISO}	Isolation Capacitance	$V_{I-O} = 0V$, freq=1.0MHz ⁽⁵⁾		0.6		pF

Notes:

- 1. No derate required to 110°C.
- 2. Functional operation under these conditions is not implied. Permanent damage may occur if the device is subjected to conditions outside these ratings.
- 3. 0.1µF bypass capacitor must be connected between pins 4 and 6.
- 4. Recommended I_{FH} is 9.3mA for operation above T_A =100°C.
- 5. Device is considered a two terminal device: Pins 1 and 3 are shorted, and Pins 4, 5, and 6 are shorted together.
- 6. 3,750 VAC_{RMS} for 1 minute duration is equivalent to 4,500 VAC_{RMS} for 1 second duration.

Electrical Characteristics (Apply over all recommended conditions)

(T_A = -40°C to +110°C, 3.0V \leq V_{CC} \leq 5.5V), unless otherwise specified. Typical value is measured at T_A = 25°C and V_{CC} = 3.3V.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
INPUT CH	IARACTERISTICS		1			
V _F	Forward Voltage	I _F = 10mA, Fig. 1	1.05	1.45	1.8	V
BV_R	Input Reverse Breakdown Voltage	I _R = 10μA	5.0			V
I _{FHL}	Threshold Input Current	$V_O = 0.6V$, $I_{OL}(sinking) = 13mA$, $T_A < 85^{\circ}C$, Fig. 2 $T_A = 85^{\circ}C$ to 110 $^{\circ}C$		3.4	5.0 7.5	mA
OUTPUT	OUTPUT CHARACTERISTICS					
V _{OL}	Logic LOW Output Voltage	I _F = rated I _{FHL} , I _{OL} (sinking) = 13mA, Fig.3		0.4	0.6	V
I _{OH}	Logic HIGH Output Current	$I_F = 250 \mu A$, $V_O = 3.3 V$, Fig. 4		8.0	50.0	μA
		$I_F = 250 \mu A, V_O = 5.0 V, Fig. 4$		2.1	30.0	μA
I _{CCL}	Logic LOW Output Supply Current	$I_F = 10$ mA, $V_{CC} = 3.3$ V, Fig. 5, 7		6.0	8.5	mA
		I _F = 10mA, V _{CC} = 5.0V, Fig. 5, 7		7.5	10.0	mA
I _{CCH}	Logic HIGH Output Supply Current	$I_F = 0$ mA, $V_{CC} = 3.3$ V, Fig. 6, 7		4.0	7.0	mA
		I _F = 0mA, V _{CC} = 5.0V, Fig. 6, 7		6.0	9.0	mA

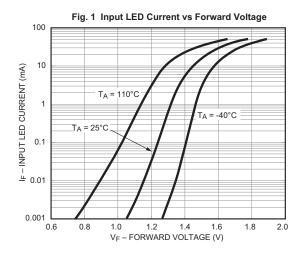
Switching Characteristics (Apply over all recommended conditions)

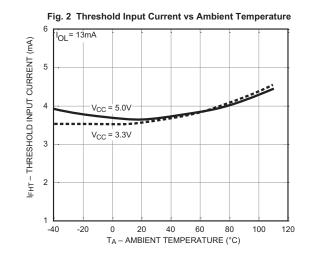
(T_A = -40°C to +110°C, 3.0V \leq V_{CC} \leq 5.5V, I_F = 7.5mA), unless otherwise specified. Typical value is measured at T_A = 25°C and V_{CC} = 3.3V

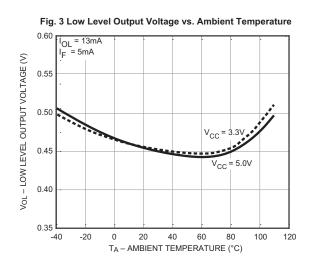
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Date Rate		$R_L = 350\Omega$			10	Mbps
t _{PHL}	Propagation Delay Time to Logic Low Output	$R_L = 350\Omega$, $C_L = 15pF$, Fig. 8 and 11		43	80	ns
t _{PLH}	Propagation Delay Time to Logic High Output	$R_L = 350\Omega$, $C_L = 15pF$, Fig. 8 and 11		50	80	ns
PWD	Pulse Width Distortion, t _{PHL} - t _{PLH}	$R_L = 350\Omega$, $C_L = 15pF$, Fig. 9		7	25	ns
t _{PSK}	Propagation Delay Skew	$R_L = 350\Omega, C_L = 15pF^{(7)}$			40	ns
t _R	Output Rise Time, (10% to 90%)	$R_L = 350\Omega$, $C_L = 15pF$, Fig. 10 and 11		20		ns
t _F	Output Fall Time, (90% to 10%)	$R_L = 350\Omega$, $C_L = 15pF$, Fig. 10 and 11		10		ns
CM _H	Common Mode Transient Immunity at Output High	$I_F = 0mA, V_O > 0.8 \times V_{CC},$ $V_{CM} = 1000V^{(8)}, Fig. 12$	20	40		kV/μs
CM _L	Common Mode Transient Immunity at Output Low	I_F = 7.5mA, V_O < 0.8V, V_{CM} = 1000V ⁽⁸⁾ , Fig. 12	20	40		kV/μs

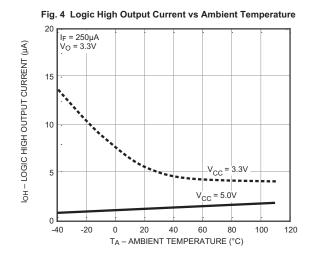
- 7. t_{PSK} is equal to the magnitude of the worst case difference in t_{PHL} and/or t_{PLH} that will be seen between any two units from the same manufacturing date code that are operated at same case temperature (±5°C), at same operating conditions, with equal loads ($R_1 = 350\Omega$ and $C_1 = 15pF$), and with an input rise time less than 5ns.
- 8. Common mode transient immunity at output high is the maximum tolerable positive dVcm/dt on the leading edge of the common mode impulse signal, Vcm, to assure that the output will remain high. Common mode transient immunity at output low is the maximum tolerable negative dVcm/dt on the trailing edge of the common pulse signal, Vcm, to assure that the output will remain low.

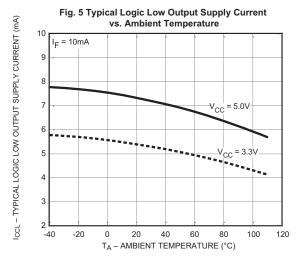
Typical Performance Curves

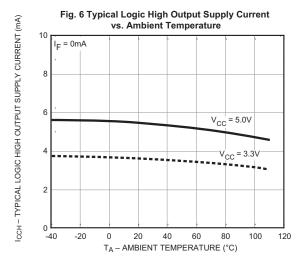












Typical Performance Curves (Continued)

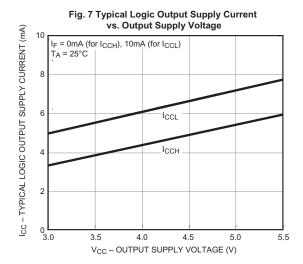


Fig. 8 Typical Propagation Delay vs. Ambient Temperature

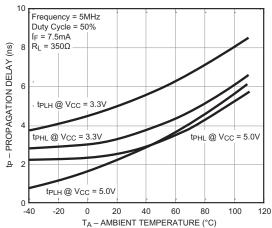


Fig. 9 Typical Pulse Width Distortion vs. Ambient Temperature

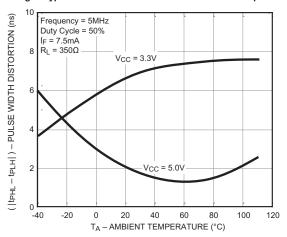
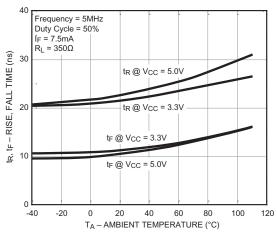
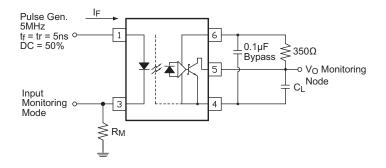


Fig. 10 Typical Rise and Fall Time vs. Ambient Temperature



Schematics



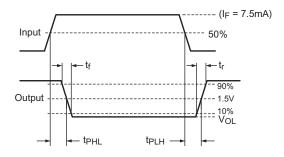
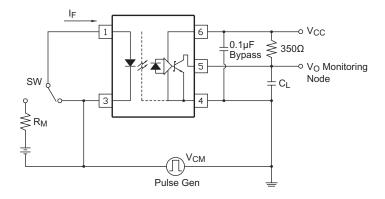


Figure 11. Test Circuit for Propagation Delay Time, Rise Time and Fall Time



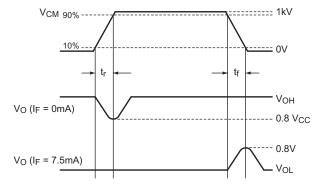
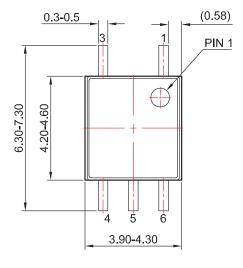
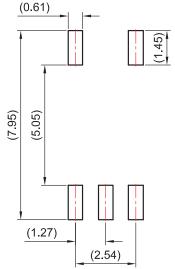
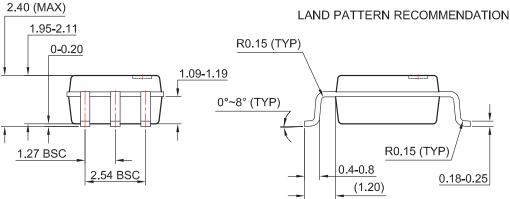


Figure 12. Test Circuit for Instantaneous Common Mode Rejection Voltage

Package Dimensions







Notes:

- 1. No standard applies to this package.
- 2. All dimensions are in millimeters.
- 3. Dimensions are exclusive of burrs, mold flash, and tie bar extrusion.
- 4. Drawings filesname and revision: MKT-MFP05A.

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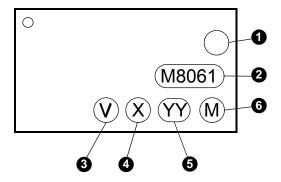
http://www.fairchildsemi.com/packaging/

Ordering Information

Part Number	Package	Packing Method
FODM8061	Mini-Flat 5-pin	(100 units per tube)
FODM8061R2	Mini-Flat 5-pin	(2,500 units per Tape and Reel)
FODM8061V	Mini-Flat 5-pin, DIN EN/IEC60747-5-5 Option	(100 units per tube)
FODM8061R2V	Mini-Flat 5-pin, DIN EN/IEC60747-5-5 Option	(2,500 units per Tape and Reel)

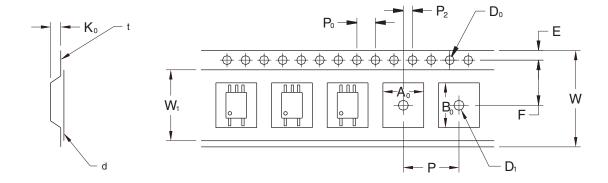
All packages are lead free per JEDEC: J-STD-020B standard.

Marking Information



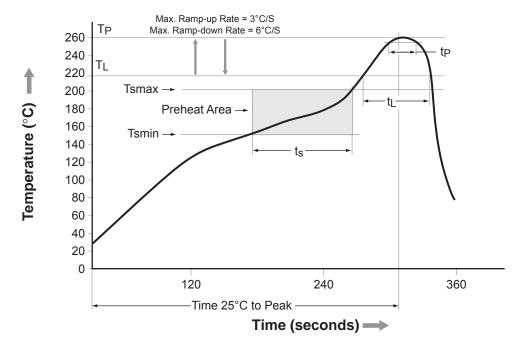
Definiti	Definitions		
1	ON Semiconductor logo		
2	Device number		
3	DIN EN/IEC60747-5-5 Option (only appears on components ordered with this option)		
4	One digit year code, e.g., '9'		
5	Two digit work week ranging from '01' to '53'		
6	Assembly package code		

Tape and Reel Dimensions



		2.54 Pitch
Description	Symbol	Dimensions (mm)
Tape Width	W	12.00 +0.30/-0.10
Tape Thickness	t	0.30 ±0.05
Sprocket Hole Pitch	P ₀	4.00 ±0.10
Sprocket Hole Diameter	D ₀	1.50 +0.10/-0.0
Sprocket Hole Location	E	1.75 ±0.10
Pocket Location	F	5.50 ±0.10
	P ₂	2.00 ±0.10
Pocket Pitch	Р	8.00 ±0.10
Pocket Dimension	A ₀	4.40 ±0.10
	B ₀	7.30 ±0.10
	K ₀	2.30 ±0.10
Pocket Hole Diameter	D ₁	1.50 Min.
Cover Tape Width	W ₁	9.20
Cover Tape Thickness	d	0.065 ±0.010
Max. Component Rotation or Tilt		10° Max.
Devices Per Reel		2500
Reel Diameter		330mm (13")

Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (t _S) from (Tsmin to Tsmax)	60–120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60–150 seconds
Peak Body Package Temperature	260°C +0°C / –5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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